

09-25-2003

FORM PTO-1594
(Rev. 6-93)

102558143

U.S. DEPARTMENT
OF COMMERCEPatent and
Trademark OfficeAtty Docket #:
ONS00496

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying part(ies):
Hsien-Te Kevin Shih

9.15.03

2. Name and address of receiving party(ies):
SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C. of
5005 East McDowell Road, Phoenix, AZ 85008Additional name(s) of conveying party(ies) is provided on attached
sheet.

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution date of
conveyance:

9/11/2003

Additional name(s) & address(es) attached?

☐ Yes☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the
application is:

9/11/2003

A. Patent Application No.(s):

10662062

B. Patent No.(s):

Additional numbers attached?

☐ Yes☒ No5. Name and address of party to whom correspondence
concerning document should be mailed:Name: SEMICONDUCTOR COMPONENTS
INDUSTRIES, L.L.C.

Internal Address: Patent Administration - A700

Street Address: P. O. Box 62890

City, State, Zip: Phoenix, Arizona 85082-2890

6. Total number of applications and patents involved:

7. Total fee (37 C.F.R. 3.41).....\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number: 501086

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of
the original document.

James J. Stipanuk

44,358

Name of Person Signing

Reg. No.

Signature

Date

Total number of pages including cover sheet, attachments, and document: 3

OMB No. 0651-0011 (exp. 4/94)

09/24/2003 LMUELLER 00000191 501086 10662062

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PATENT
REEL: 014513 FRAME: 0068

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

Name _____ of (City/State/Country)
Hsien-Te Kevin Shih Phoenix, Arizona, USA;

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a corporation of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States of America in and to certain inventions relating to improvements in

METHOD AND CIRCUIT FOR OPTIMIZING POWER EFFICIENCY IN A DC-DC CONVERTER

(Attorney Docket No. ONS00496),
described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

PATENT
REEL: 014513 FRAME: 0070